



PRODUCT DESCRIPTION

HYSOL GR30 is a semiconductor grade mold compound providing the following product characteristics:

Technology	Epoxy
Cure	Heat cure
Appearance	Black
Filler Type	Fused & Spherical Silica
Filler Weight, %	80 $\pm$ 1
Filler cut	75 μ m
Application	Mold Compound
Target Package	Energy Vehicle Rotor
Product Benefits	• Friendly UPH • Good Workability • Excellent Oil Resistance • Narrow Gap Filling (100μm)

HYSOL GR30 is a thermosetting material used to fix motor rotors. GR30 is formulated to apply in various energy vehicle rotor.

HYSOL GR30 meets UL 94 V-0 Flammability.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Property	Typical Value
Spiral Flow, @175°C, cm	90
Gel Time, @175°C, seconds	20
Shelf Life, @5°C, days	183
Specific Gravity, g/cm ³	1.88

TYPICAL PROCESS DATA

Handling	Typical Value
Thawing Time, hours	20 to 24
Thawing Temperature, °C	20 to 30
Usage Time after Thawing, hours	48 @25°C
Preheat temperature, °C	60 to 80
Rotor Core Temperature, °C	150 to 180
Molding Temperature, °C	175 to 185
Transfer Time, seconds	5 to 15

HYSOL GR30 has been formulated to provide the best possible moldability and as wide a molding latitude as possible. Although molding and curing conditions will vary from situation to situation, recommended starting ranges are shown above.

Please contact Hysol Huawei Technical Service for alternative process parameters if needed.

TYPICAL PROPERTIES OF CURED MATERIAL

All measurements are taken at 25°C unless otherwise noted. All physical, electrical and analytical measurements are taken on specimens cured for 120 seconds @175°C with post cure of 6 hours @175°C, unless otherwise specified.

Physical Property	Typical Value
Glass Transition Temperature, °C:	170
CTE 1, ppm/°C:	11
CTE 2, ppm/°C:	55
Flexural Modulus @ 25°C (MPa)	15800
Flexural Strength @ 25°C (MPa)	120
Tensile Strength @ 25°C (MPa)	80
CTI (V)	600
Thermal Conductivity, W/(m·K)	0.8

Application Specific Properties

Extractable Ionic Content, ppm:	
Chloride (Cl-)	10
Sodium (Na+)	4

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

Not for product specifications

The technical data contained herein are intended as reference only. Please contact Hysol Huawei Electronics Co., Ltd. quality department for assistance and recommendations on specifications for this product.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: 5°C or below, in closed containers.
After removal from cold storage, the material MUST be allowed to come to room temperature, in the sealed container, to avoid moisture contamination. The suggested waiting time for a standard 15 kg carton box is 24 hours.

Material removed from containers may be contaminated during use. Do not return product to the original container.

Hysol Huawei Electronics Co., Ltd. cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact Hysol Huawei Electronics Co., Ltd. Technical Service or Customer Service Representative.

Disclaimer

NOTE

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our best knowledge and experience of the product as at the date of this TDS.

Hysol Huawei Electronics Co., Ltd. is, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet regarding the concerned product is excluded.

TRADEMARK USAGE

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